

SOT576-1

plastic thermal enhanced quad flat package; 160 leads (lead length 1.6 mm); body 28 x 28 x 3.4 mm; high stand-off height; heatsink

8 February 2016

Package information

1. Package summary

Terminal position code	Q (quad)
Package type descriptive code	HQFP160
Package type industry code	HQFP160
Package style descriptive code	HQFP (thermal enhanced quad flat package)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	20-2-2003

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	27.9	-	28	28.1	mm
E	package width	27.9	-	28	28.1	mm
A	seated height	[tbd]	-	4.07	4.07	mm
A ₂	package height	3.2	-	3.4	3.6	mm
n ₂	actual quantity of termination	-	-	160	-	



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2. Package outline

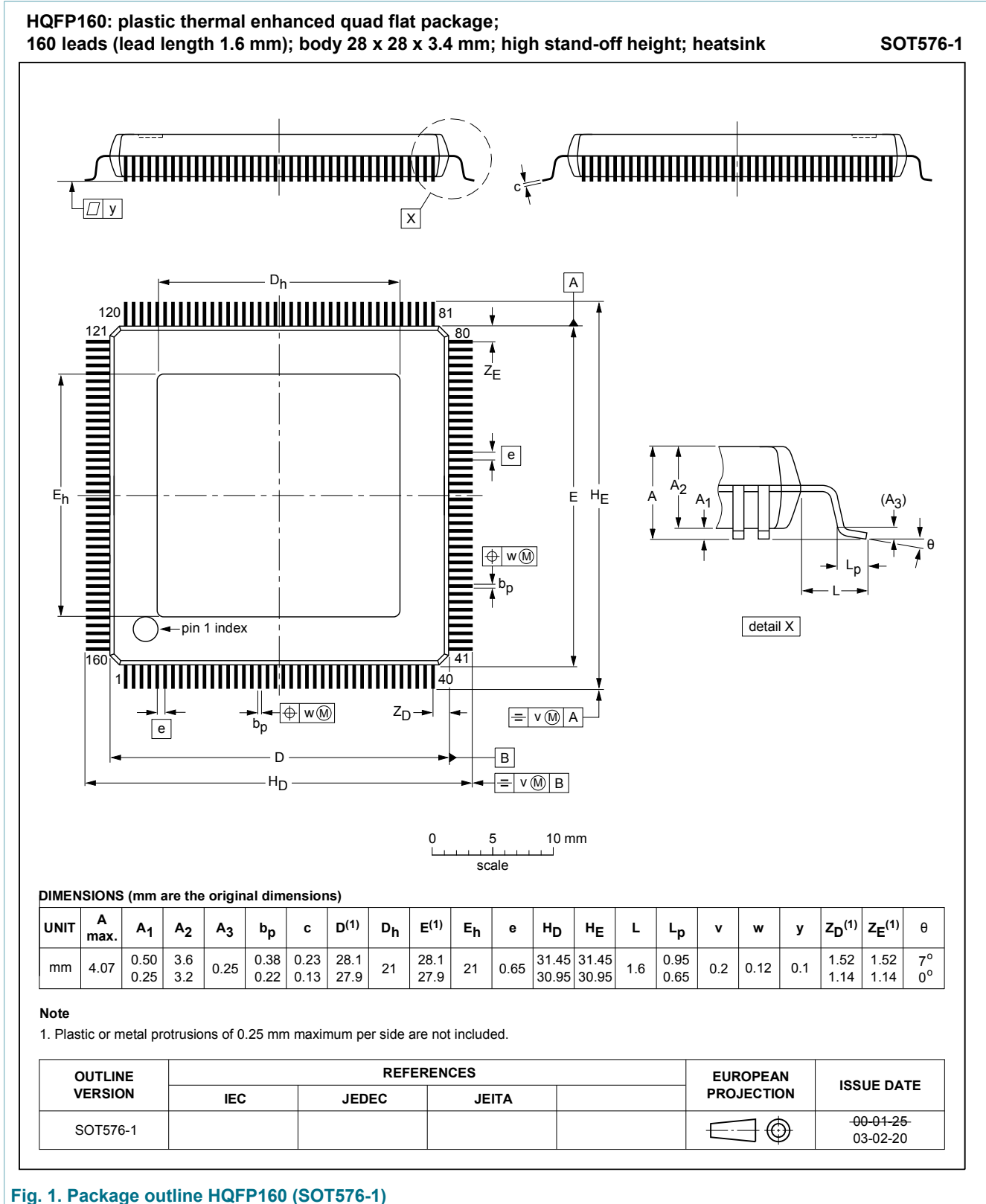


Fig. 1. Package outline HQFP160 (SOT576-1)

plastic thermal enhanced quad flat package;160
leads (lead length 1.6 mm); body 28 x 28 x 3.4
mm; high stand-off height; heatsink

3. Soldering

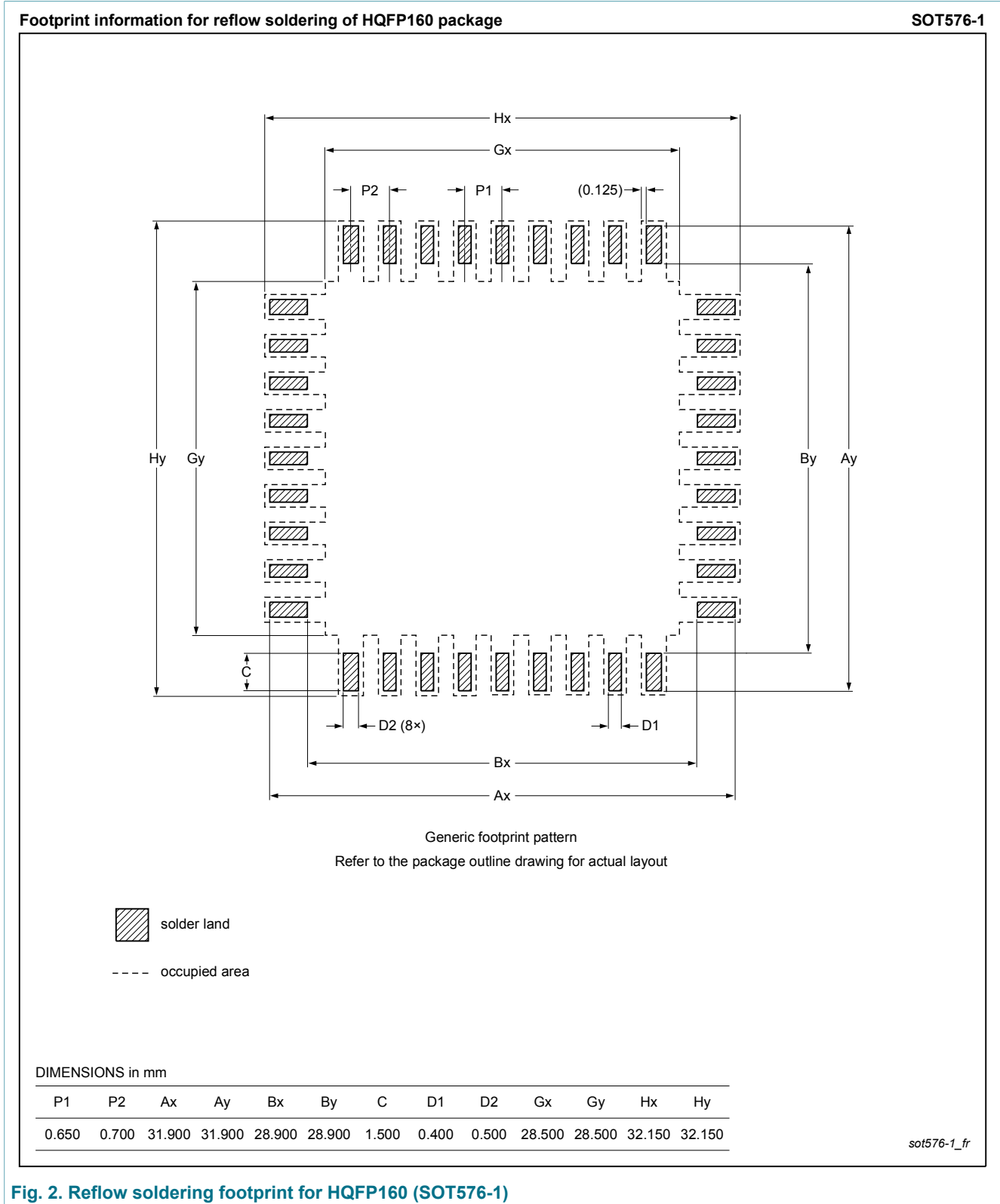


Fig. 2. Reflow soldering footprint for HQFP160 (SOT576-1)

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4. Legal information

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